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Diodes Incorporated DMN2300UFB-7B

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Datasheet of DMN2300UFB-7B - MOSFET N-CH 20V 1.32A 3DFN

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DMN2300UFB

#### 20V N-CHANNEL ENHANCEMENT MODE MOSFET

#### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub> max T <sub>A</sub> = +25°C	
	$175 m\Omega @ V_{GS} = 4.5V$	1.30A	
20V	$240 \text{m}\Omega$ @ $V_{GS}$ = $2.5V$	1.11A	
	$360 \text{m}\Omega$ @ $V_{GS}$ = 1.8 $V$	0.91A	

#### **Features and Benefits**

- Footprint of just 0.6mm<sup>2</sup> thirteen times smaller than SOT23
- 0.5mm profile ideal for low profile applications
- On resistance <200mΩ @ V<sub>GS</sub> = 4.5V
- Low Gate Threshold Voltage
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- ESD Protected Gate 2KV
- Qualified to AEC-Q101 Standards for High Reliability

#### **Description and Applications**

This MOSFET is designed to minimize the on-state resistance (R<sub>DS(on)</sub>) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Load Switch

#### **Mechanical Data**

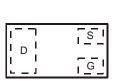
- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound;
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe; Solderable per MIL-STD-202, Method 208 (4)
- Weight: 0.001 grams (Approximate)



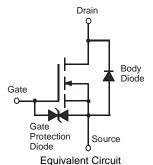




**Bottom View** 



Top View Internal Schematic



#### **Ordering Information** (Note 4)

Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMN2300UFB-7	NI	7	8	3,000
DMN2300UFB-7B	NI	7	8	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

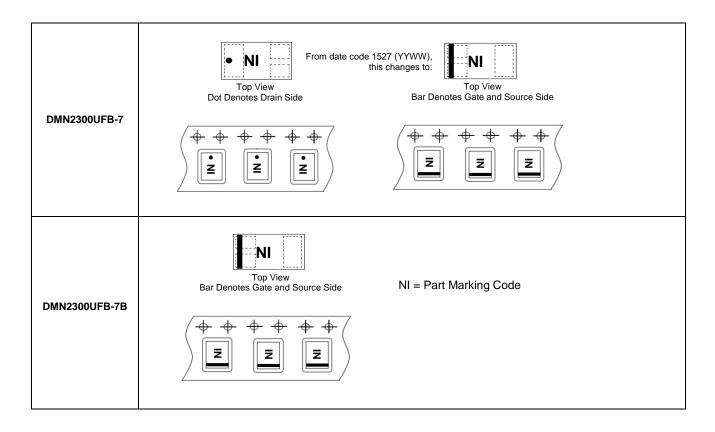
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# **Marking Information**



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#### **Maximum Ratings** (@T<sub>A</sub> = +25°C unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V <sub>DSS</sub>	20	V
Gate-Source Voltage			V <sub>GSS</sub>	±8	V
Continuous Drain Current	Steady State	$T_A = +25^{\circ}\text{C (Note 5)}$ $T_A = +85^{\circ}\text{C (Note 5)}$ $T_A = +25^{\circ}\text{C (Note 6)}$	I <sub>D</sub>	1.32 0.94 1.78	А
Pulsed Drain Current (Note 7)			I <sub>DM</sub>	8	А

### Thermal Characteristics (@T<sub>A</sub> = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	0.468	W
Power Dissipation (Note 6)	P <sub>D</sub>	1.2	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	267	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	R <sub>0JA</sub>	104	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

#### Electrical Characteristics (@TA = +25°C unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)					•		
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	-	-	V	$V_{GS} = 0V, I_{D} = 10\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	-	-	1	μΑ	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	-	-	10	μΑ	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.45	-	0.95	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
		-	-	175		$V_{GS} = 4.5V, I_D = 300mA$	
Static Drain-Source On-Resistance	R <sub>DS (ON)</sub>	-	-	240	mΩ	$V_{GS} = 2.5V, I_D = 250mA$	
		-	-	360		$V_{GS} = 1.8V, I_D = 100mA$	
Forward Transfer Admittance	Y <sub>fs</sub>	40	-	-	mS	$V_{DS} = 3V, I_{D} = 30mA$	
Diode Forward Voltage	V <sub>SD</sub>	-	0.7	1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 300mA	
DYNAMIC CHARACTERISTICS						•	
Input Capacitance	C <sub>iss</sub>	-	67.62	-	pF	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
Output Capacitance	Coss	-	9.74	-	pF	$V_{DS} = 20V, V_{GS} = 0V,$ - f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	-	7.58	-	pF	- T = 1.0IVIHZ	
Gate Resistance	Rg	-	68.51	-	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge	Qq	-	0.89	-	nC		
Gate-Source Charge	Q <sub>gs</sub>	-	0.14	-	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$ $I_{D} = 1A$	
Gate-Drain Charge	Q <sub>qd</sub>	-	0.16	-	nC		
Turn-On Delay Time	t <sub>D(on)</sub>	-	4.92	-	ns		
Turn-On Rise Time	tr	-	6.93	-	ns	$V_{DS} = 10V, I_{D} = 1A$ $V_{GS} = 4.5V, R_{G} = 6\Omega$	
Turn-Off Delay Time	t <sub>D(off)</sub>	-	21.71	-	ns		
Turn-Off Fall Time	t <sub>f</sub>	-	10.62	-	ns		

Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 25mm X 25mm square copper plate.
- 7. Device mounted on minimum recommended pad layout test board, 10µs pulse duty cycle = 1%.
- 8. Short duration pulse test used to minimize self-heating effect.

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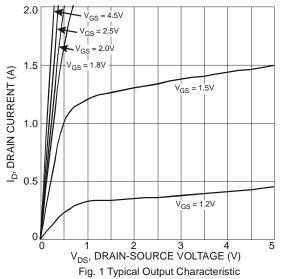
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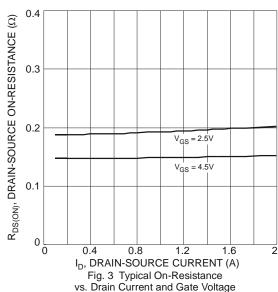


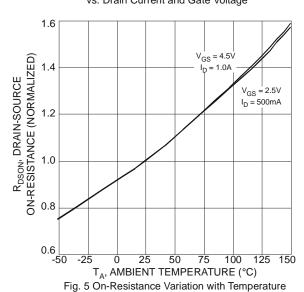
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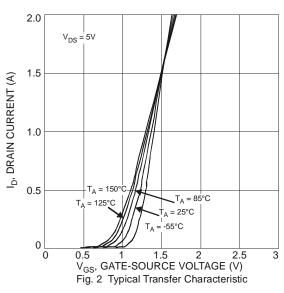


#### DMN2300UFB









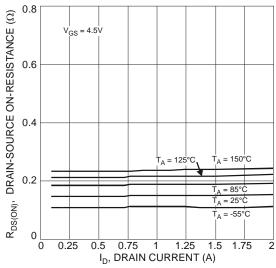


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

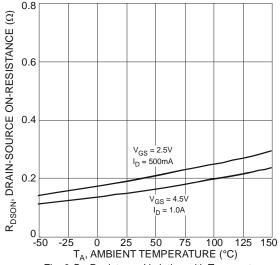
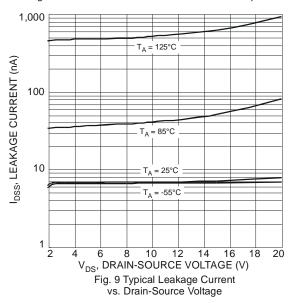


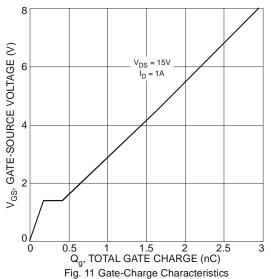
Fig. 6 On-Resistance Variation with Temperature



#### 1.2 (E) 1.0 0.8 1.0 0.8 1.0 0.8 1.0 0.4 1.0 0.4 1.0 0.4 1.0 0.4 1.0 0.4 1.0 0.4 1.0 0.4 1.0 0.4 1.0 0.4 1.0 0.4 1.0 0.4 1.0 0.5 1.

Fig. 7 Gate Threshold Variation vs. Ambient Temperature

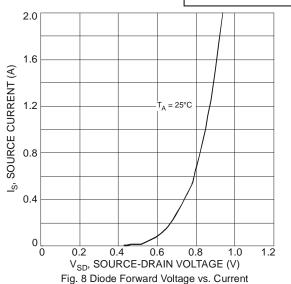


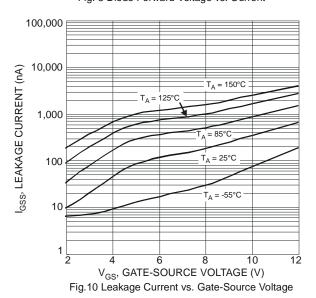


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#### DMN2300UFB





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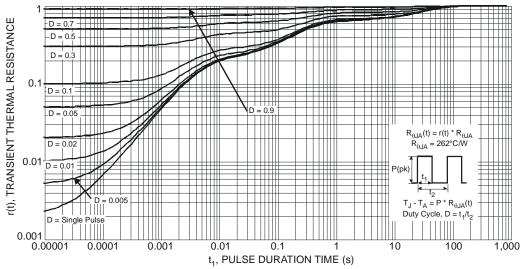


Fig. 12 Transient Thermal Response

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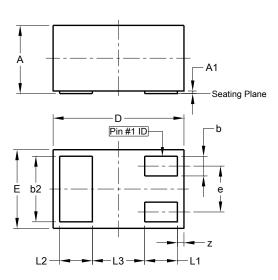




DMN2300UFB

#### **Package Outline Dimensions**

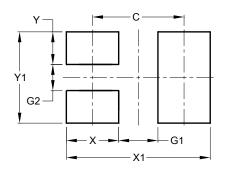
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X1-DFN1006-3					
Dim	Min	Max	Тур		
Α	0.47	0.53	0.50		
A1	0.00	0.05	0.03		
b	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.075	1.00		
E	0.55	0.675	0.60		
е	-	-	0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3	-	-	0.40		
Z	0.02	0.08	0.05		
All Dimensions in mm					

# Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Y	0.25
Y1	0.70



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